

Dimensions Chip Size

C1206X391J2TACTU

Aliases (C1206X391J2TAC7800)

General Information

Series

Style

Description

Features

RoHS

SMD Comm X8G HT150C Flex, Ceramic, 390 pF, 5%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm

SMD Comm X8G HT150C Flex

SMD, MLCC, High Temperature,

High Temperature, Ultra-Stable

SMD Chip

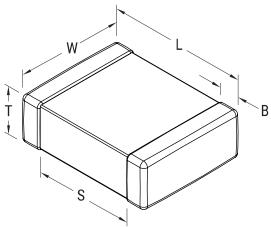
Ultra-Stable

Flexible Termination

Yes

No No 15 mg 78 Weeks

1



S Click here for the 3D model.	the 3D model.	Termination Marking AEC-Q200 Typical Component Weight Shelf Life MSL
		Specifications
	1206	Capacitance
	3.3mm +/-0.4mm	Measurement Condition

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W	1.6mm +/-0.35mm	
Т	0.78mm +/-0.20mm	
S	1.5mm MIN	
В	0.6mm +/-0.25mm	
Burlanda a Caradita attana		

Packaging Specifications		
Packaging	T&R, 180mm, Plastic Tape	
Packaging Quantity	4000	

Specifications	
Capacitance	390 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	5%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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